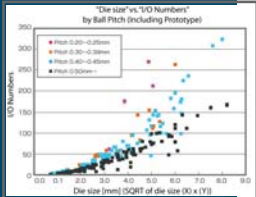
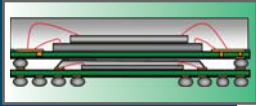


Advanced Packaging Update: Market and Technology Trends

Vol. 4, 2008



Volume 4 of the Advanced Packaging Update for 2008 features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into laminate, flex circuit, and leadframe substrates. Unit growth projections are provided for stacked die CSP and package-on-package (PoP) shipments. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry. A market growth analysis based on input from both captive and merchant assembly operations is provided. The impact of the downturn on unit volumes is explained. Key applications and drivers for the recovery are highlighted. A section on co-design is included.

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